



SOT1571-6

HLQFP48, plastic, thermal enhanced low profile quad flat package; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 1.4 mm body; 4.4 mm x 4.4 mm exposed pad

3 August 2018

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HLQFP48
Package style descriptive code	HLQFP (thermal enhanced low profile quad flat package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	19-07-2018
Manufacturer package code	98ASA00945D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	7	-	mm
package width	-	7	-	mm
package height	-	1.4	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	48	-	



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2 Package outline

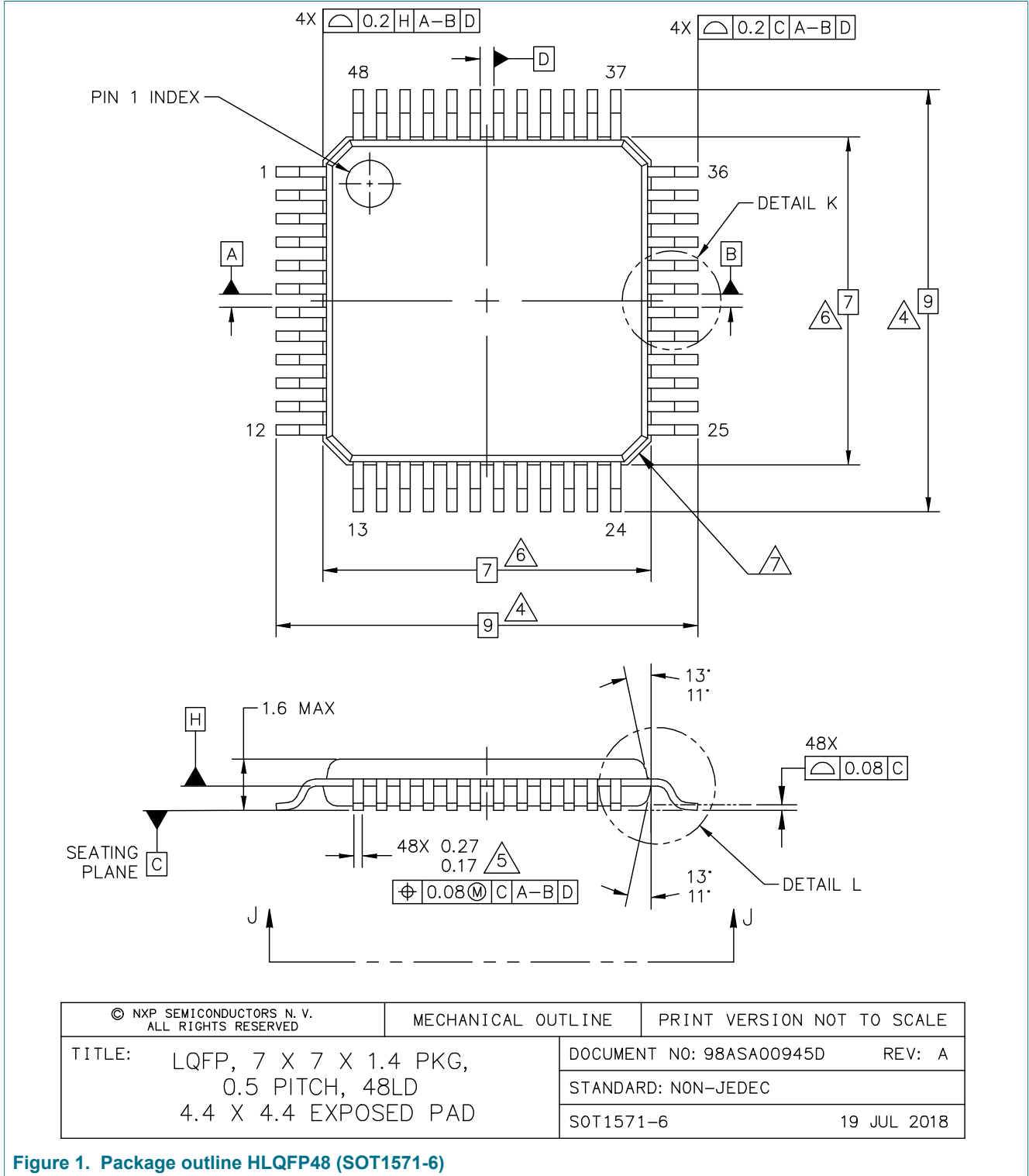


Figure 1. Package outline HLQFP48 (SOT1571-6)

HLQFP48, plastic, thermal enhanced low profile quad flat package; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 1.4 mm x 1.4 mm body; 4.4 mm x 4.4 mm exposed pad

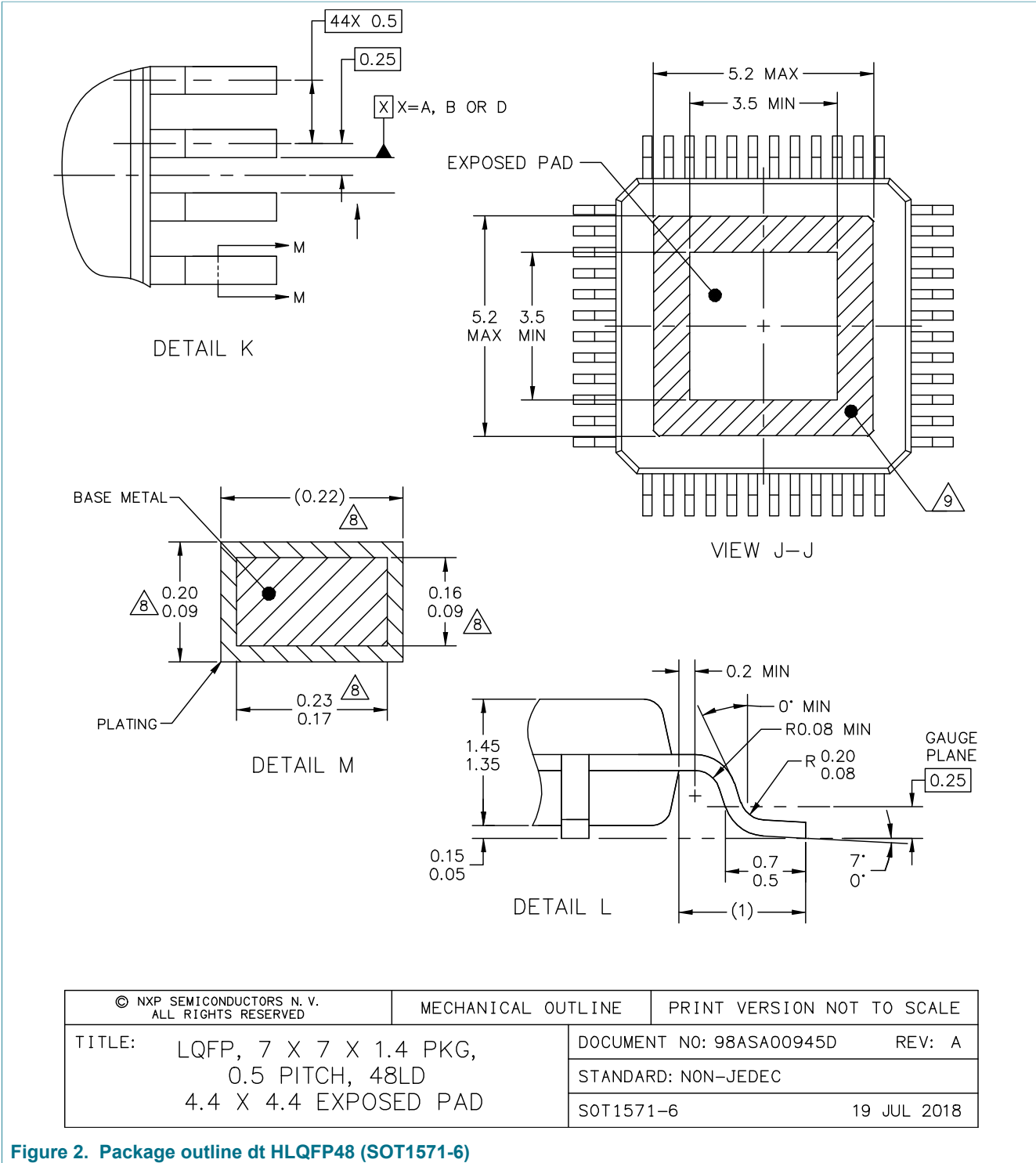


Figure 2. Package outline dt HLQFP48 (SOT1571-6)

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NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
4. DIMENSION TO BE DETERMINED AT SEATING PLANE C.
5. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE UPPER LIMIT BY MORE THAN 0.08MM AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD SHALL NOT BE LESS THAN 0.07MM.
6. THIS DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25MM PER SIDE. THIS DIMENSION IS MAXIMUM PLASTIC BODY SIZE DIMENSION INCLUDING MOLD MISMATCH.
7. EXACT SHAPE OF EACH CORNER IS OPTIONAL.
8. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.1MM AND 0.25MM FROM THE LEAD TIP.
9. HATCHED AREA REPRESENTS POSSIBLE MOLD FLASH ON EXPOSED PAD.
10. KEEP OUT ZONE REPRESENTS AREA ON PCB THAT MUST NOT HAVE ANY EXPOSED METAL (TRACE/VIA) FOR PCB ROUTING DUE TO THE POSSIBILITY OF SHORTING TO TIE BAR/EXPOSED PAD.

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TITLE: LQFP, 7 X 7 X 1.4 PKG, 0.5 PITCH, 48LD 4.4 X 4.4 EXPOSED PAD	DOCUMENT NO: 98ASA00945D	REV: A
	STANDARD: NON-JEDEC	
	SOT1571-6	19 JUL 2018

Figure 3. Package outline note HLQFP48 (SOT1571-6)

HLQFP48, plastic, thermal enhanced low profile quad flat package; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 1.4 mm x 1.4 mm body; 4.4 mm x 4.4 mm exposed pad

3 Soldering

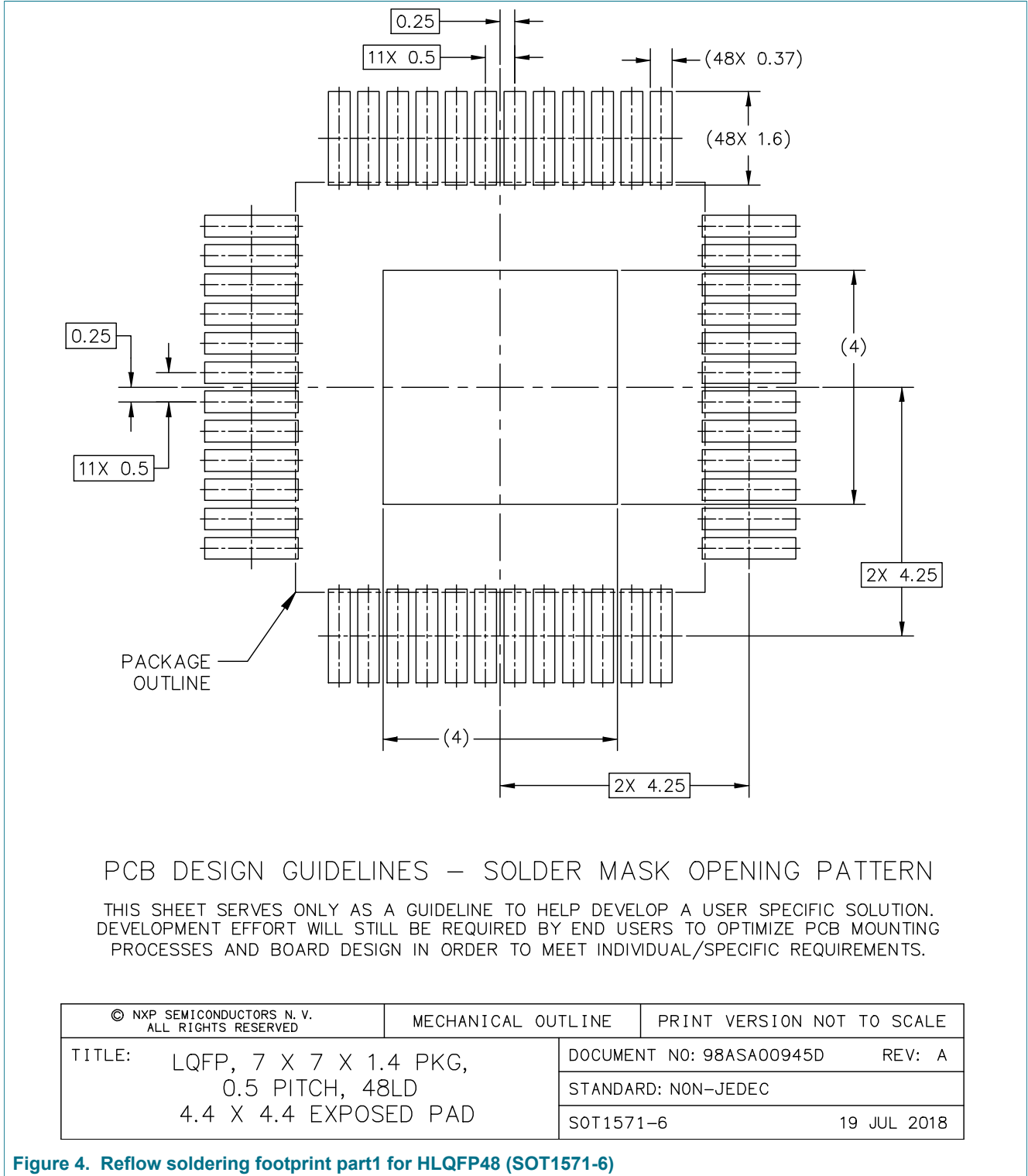
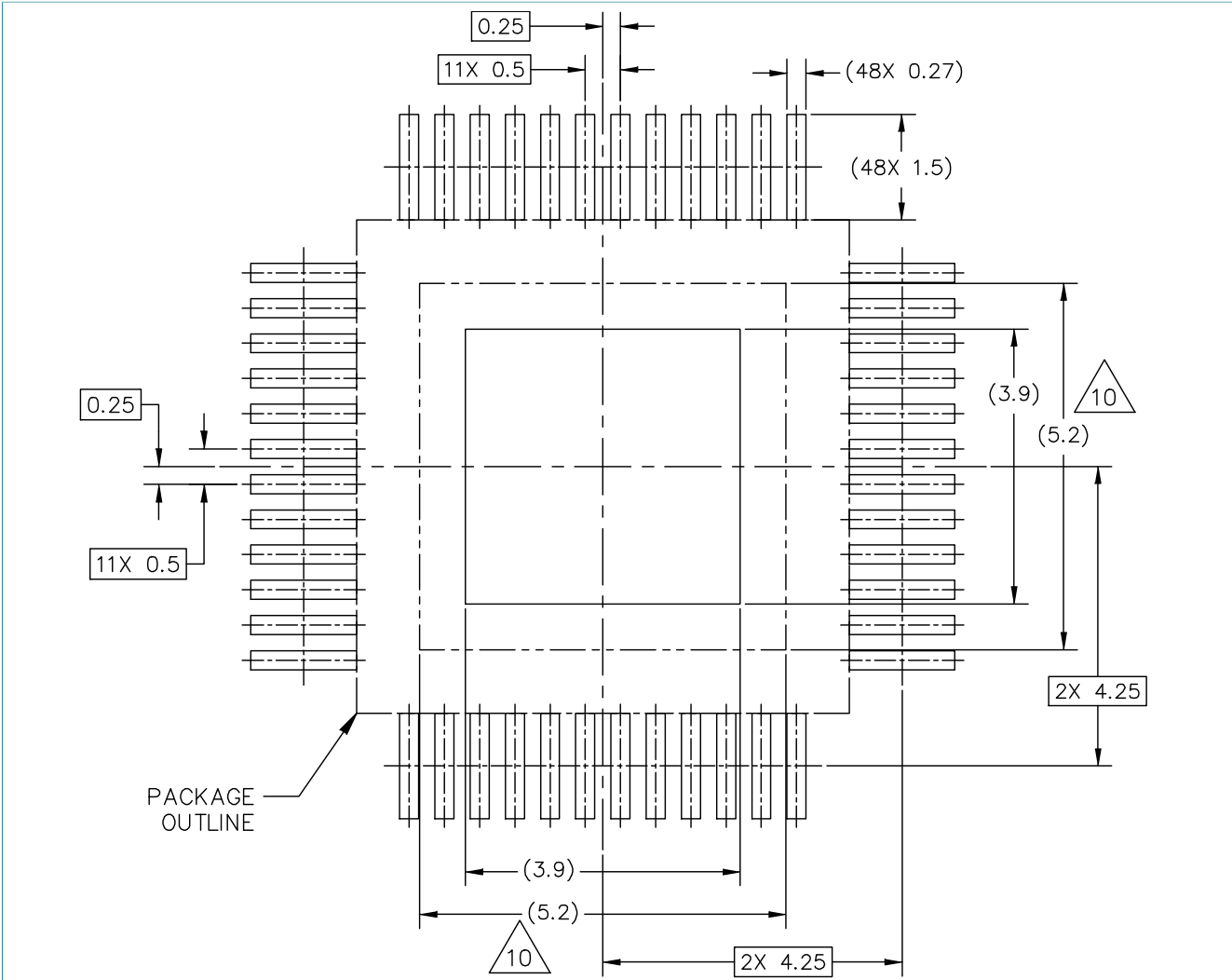


Figure 4. Reflow soldering footprint part1 for HLQFP48 (SOT1571-6)

HLQFP48, plastic, thermal enhanced low profile quad flat package; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 1.4 mm x 1.4 mm body; 4.4 mm x 4.4 mm exposed pad



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCFSSES AND BOARD DFSIGN IN ORDFR TO MFFT INDIVIDUAL/SPFCIFIC RFQUIRFMNTS.

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Figure 5. Reflow soldering footprint part2 for HLQFP48 (SOT1571-6)

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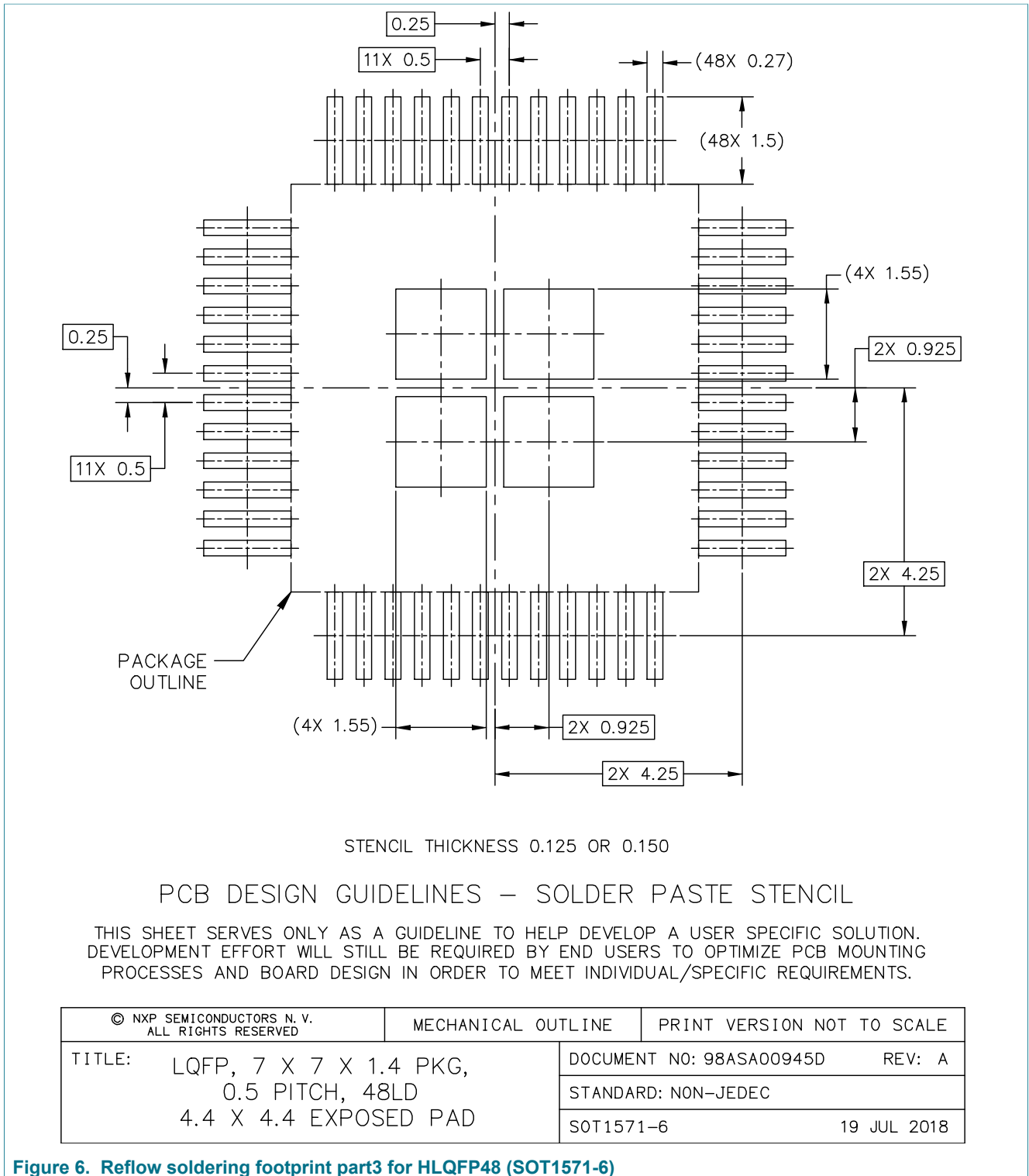


Figure 6. Reflow soldering footprint part3 for HLQFP48 (SOT1571-6)

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Contents

1	Package summary	1
2	Package outline	2
3	Soldering	5
4	Legal information	8